

# Organizational Chart

**Europe | Japan | North America | China | Korea | Taiwan**

**Last Updated: November 2019  
v1**

# **Global Technical Committee (GTC) and Technical Committee (TC) Chapters**

---



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	EH&S				TCC		TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committees

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committees

Note 1: An underlined Locale has an RSC and may also be referred as a “Region” (e.g., “Europe Region”)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)



Global Technical Committee	Locale					
	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Traceability			TCC		TCC	
Information & Control		TCC	TCC	TCC	TCC	TCC
Metrics		TCC	TCC		TCC	
Physical Interfaces & Carriers		TCC	TCC		TCC	
Automation Technology		TCC	TCC			TCC
Photovoltaic	TCC		TCC		TCC	TCC
PV Materials	TCC	TCC	TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee

Note 1: An underlined Locale has an RSC and may also be referred to as “a Region” (e.g., Europe Region)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)

\*In NA, Mircopatterining is traditionally called Microlithography



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Micropatterning (Microlithography*)						TCC
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials		TCC	TCC	TCC		TCC	
HB-LED		TCC				TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”)

\*In NA, Micropatterning is traditionally called Microlithography

\*\*3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017

# **Regional Standards Committee (RSC) Organizations**

---

# SEMI Europe RSC Organization

**Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting**  
**Vice-Chair: Frank Petzold – Trustsec**



**Europe Chapter of Automation Technology  
Global Technical Committee**

C: Christian Hoffmann – PEER Group

**Europe Chapter of Liquid Chemicals  
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of Physical Interfaces & Carriers  
Global Technical Committee**

C: Frank Petzold – Trustsec

**Europe Chapter of  
Compound Semiconductor Materials  
Global Technical Committee**

C: Arnd Weber – SiCrystal

**Europe Chapter of Information & Control  
Global Technical Committee**

C: Frank Petzold – Trustsec

**Europe Chapter of PV Materials  
Global Technical Committee**

C: Peter Wagner – Consultant  
C: Christian Hagendorf – Fraunhofer CSP

**Europe Chapter of Gases  
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of Metrics  
Global Technical Committee**

C: Open

**Europe Chapter of Silicon Wafer  
Global Technical Committee**

C: Werner Bergholz – International Standards Consulting  
C: Peter Wagner – Consultant  
C: Fritz Passek - Siltronic

# SEMI Japan RSC Organization

**Co-Chairs: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology**  
**Vice-Chair: Supika Mashiro – TEL**





# SEMI North America (NA) RSC Organization – NA Locale

**Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering**  
**Vice-Chair: Brian Rubow – Cimetrix**



**NA Chapter of 3D Packaging & Integration  
Global Technical Committee**  
 C: Sesh Ramaswami – Applied Materials  
 C: Chris Moore – Covalent Metrology  
 C: Bill Kerr – Evergreen Enhancement

**NA Chapter of Gases  
Global Technical Committee**  
 C: Mohamed Saleem – Brooks Instrument

**NA Chapter of Metrics  
Global Technical Committee**  
 C: David Bouldin – Fab Consulting  
 C: Mark Frankfurth – Cymer  
 C: Vladimir Kraz – BestESD

**NA Chapter of Silicon Wafer  
Global Technical Committee**  
 C: Dinesh Gupta – STA  
 C: Noel Poduje – SMS  
 VC: Mike Goldstein

**NA Chapter of Automated Test Equipment  
Global Technical Committee**  
 C: Mark Roos – Roos Instruments  
 C: Stacey Ajouri – Texas Instruments

**NA Chapter of HB-LED  
Global Technical Committee**  
 C: Mike Feng – Silian  
 C: Chris Moore – Covalent Metrology  
 C: Andrew Kim – InnovationforX

**NA Chapter of Microlithography  
Global Technical Committee**  
 C: Bryan Barnes – NIST

**NA Chapter of Traceability  
Global Technical Committee**  
 C: Yaw Obeng – NIST  
 C: David Huntley – PDF Solutions

**NA Chapter of  
Compound Semiconductor Materials  
Global Technical Committee**  
 C: Russ Kremer – Freiberger Compound Materials  
 C: James Oliver – Northrop Grumman

**NA Chapter of Information & Control  
Global Technical Committee**  
 C: Jack Ghiselli – Ghiselli Consulting  
 C: Brian Rubow – Cimetrix  
 C: James Moyne – AMAT/ University of Michigan

**NA Chapter of Photovoltaic  
Global Technical Committee**  
 C: James Moyne – AMAT/University of Michigan

**NA RSC  
Technical Architect Board**  
 C: James Moyne – AMAT/ University of Michigan  
 C: Yaw Obeng – NIST

**NA Chapter of  
Environmental, Health & Safety  
Global Technical Committee**  
 C: Chris Evanston – Salus Engineering  
 C: Sean Larsen – Lam Research  
 C: Bert Planting – ASML

**NA Chapter of Liquid Chemicals  
Global Technical Committee**  
 C: Don Hadder – Intel  
 C: Steve Rogers – KMG Chemicals  
 C: Laura Ledenbach – PeroxyChem  
 C: Koh Murai – Mega Fluid Systems

**NA Chapter of PV Materials  
Global Technical Committee**  
 C: Hugh Gotts – Air Liquide

**NA Chapter of Facilities  
Global Technical Committee**  
 C: Steve Lewis – BW Design Group

**NA Chapter of MEMS/NEMS  
Global Technical Committee**  
 C: Steve Martell – Nordson SONOSCAN

**NA Chapter of  
Physical Interfaces & Carriers  
Global Technical Committee**  
 C: Matt Fuller – Entegris  
 C: Melvin Jung – Intel

# SEMI North America RSC Organization

## China Locale

**Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering**  
**Vice-Chair: Brian Rubow – Cimatrix**

---

<p><b>China Chapter of Compound Semiconductor Materials Global Technical Committee</b> C: Jiangbo Wang – HC SEMITEK C: Guoyou Liu – CRRC TIMES</p>	<p><b>China Chapter of Photovoltaic Global Technical Committee</b> C: Guangchun Zhang – CanadianSolar</p>
<p><b>China Chapter of HB-LED Global Technical Committee</b> C: Hongbo Zuo – AURORA C: Jiangbo Wang – HC SEMITEK</p>	<p><b>China Chapter of PV Materials Global Technical Committee</b> C: Guangchun Zhang – CanadianSolar</p>

# SEMI North America RSC Organization

## Korea Locale

**Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering**  
**Vice-Chair: Brian Rubow – Cimetrix**

---

<p><b>Korea Chapter of Facilities Global Technical Committee</b> C: Kwang Sun Kim – KUT</p>	<p><b>Korea Chapter of FPD Metrology Global Technical Committee</b> C: Jongho Chong – Samsung Display C: Kyungjin Kang – LG Electronics</p>
<p><b>Korea Chapter of FPD Materials &amp; Components Global Technical Committee</b> C: Jongseo Lee – Dell C: Il-Ho (William) Kim – Light Measurement Solution</p>	<p><b>Korea Chapter of Information &amp; Control Global Technical Committee</b> C: Hyungsu Kim – Doople C: Chul Hong Ahn – SK hynix C: Gun Woo Lee – Lam Research</p>

# SEMI North America RSC Organization

## Taiwan Locale

**Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering**  
**Vice-Chair: Brian Rubow – Cimatrix**

**Taiwan Chapter of  
3D Packaging & Integration  
Global Technical Committee**

C: Wendy Chen – King Yuan Electronics  
C: Chien-Chung Lin – ITRI  
C: Roger Hwang – ASE

**Taiwan Chapter of  
Environmental Health & Safety  
Global Technical Committee**

C: Shuh-Woei Yu – SAHTECH

**Taiwan Chapter of Information & Control  
Global Technical Committee**

C: Scott Yu – TSMC

**Taiwan Chapter of Automation Technology  
Global Technical Committee**

C: K.C. Chou – ASE  
C: Jen-Hui Tsai – ITRI  
C: Gwo-Sheng Peng – ITRI/CMS  
C: Jui-Ming Hua – MIRDC

**Taiwan Chapter of Flat Panel Display  
Global Technical Committee**

C: Jia-Ming Liu – TDMDA

**Taiwan Chapter of Photovoltaic  
Global Technical Committee**

C: T.C. Wu – CMS/ITRI  
C: Ray Sung – UL Taiwan  
C: C.C. Lin – PV Guider

**ISC Taiwan Advisor**

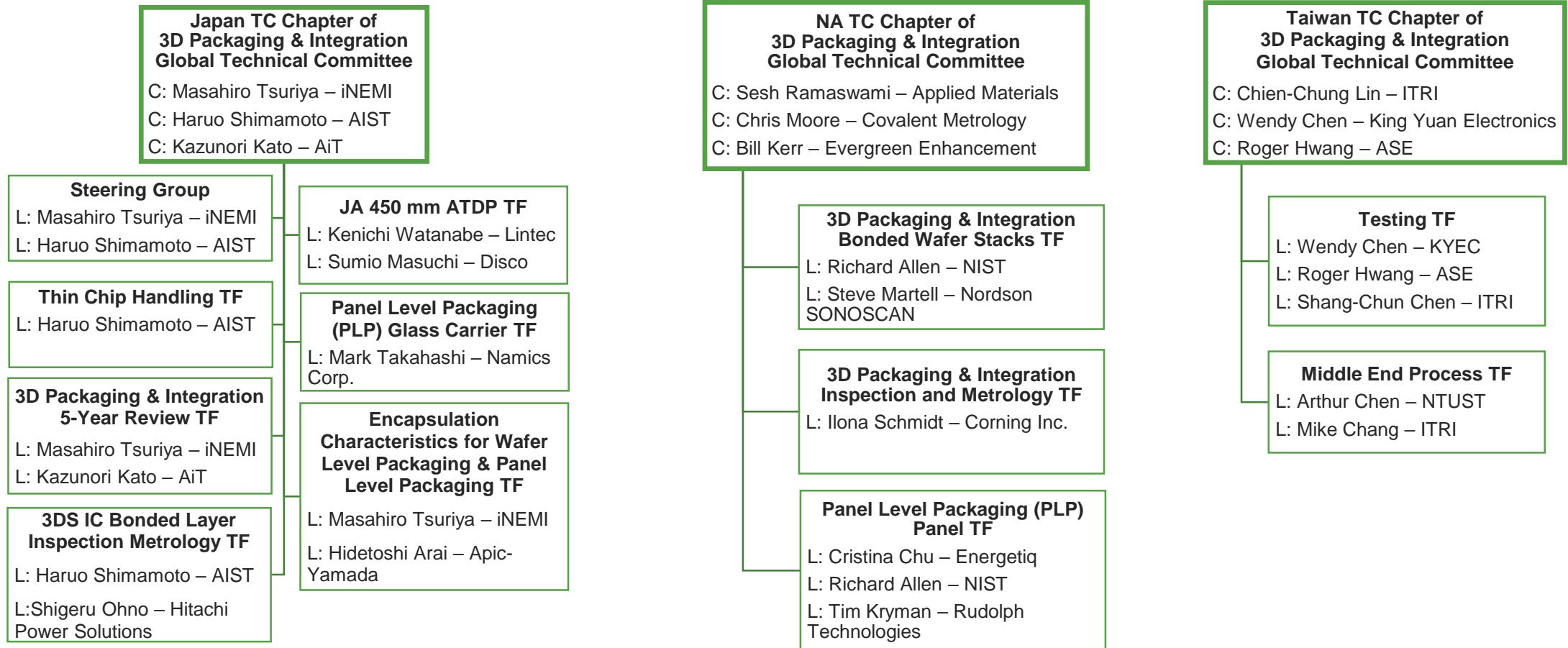
Tzeng-Yow Lin – CMS/ITRI

# Organization of Each TC Chapter

TF = Task Force | WG = Working Group

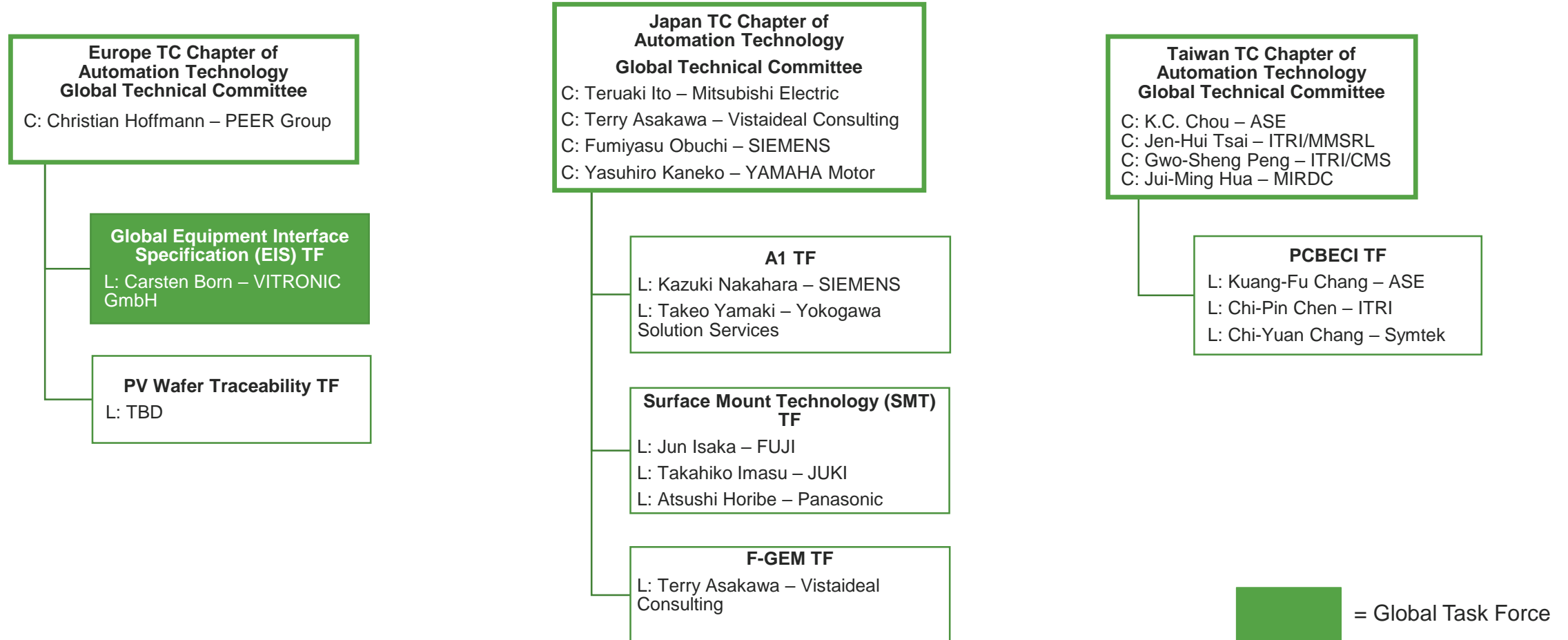
---

# 3D Packaging & Integration (3DP&I) Global Technical Committee



# Automation Technology (AT)

## Global Technical Committee



# Automated Test Equipment (ATE) Global Technical Committee



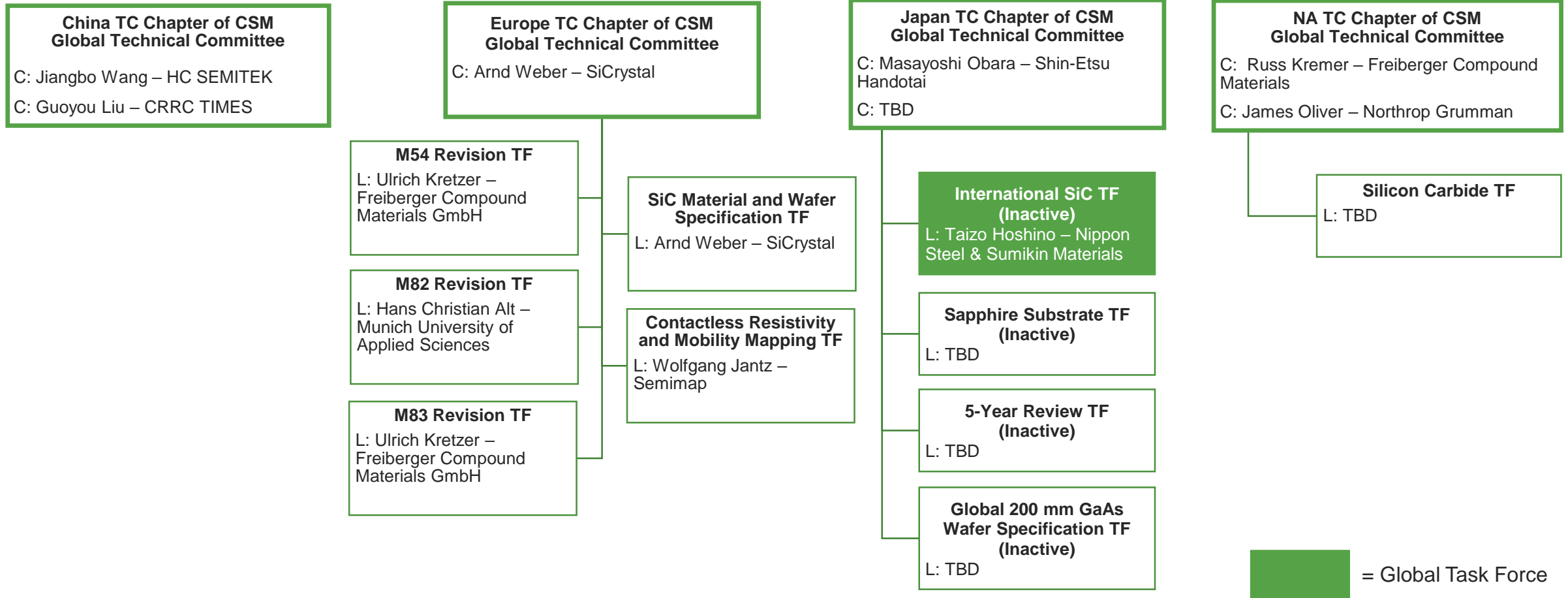
**NA TC Chapter of  
Automated Test Equipment  
Global Technical Committee**  
C: Mark Roos – Roos Instruments  
C: Stacey Ajouri – Texas Instruments  
C: Laurent Bonneval – Teradyne

**Rich Interactive Database (RITdb) TF**  
L: Mark Roos – Roos Instruments  
L: Stacey Ajouri – Texas Instruments

**Tester Event Messaging for  
Semiconductors (TEMS) TF**  
L: Laurent Bonneval – Teradyne

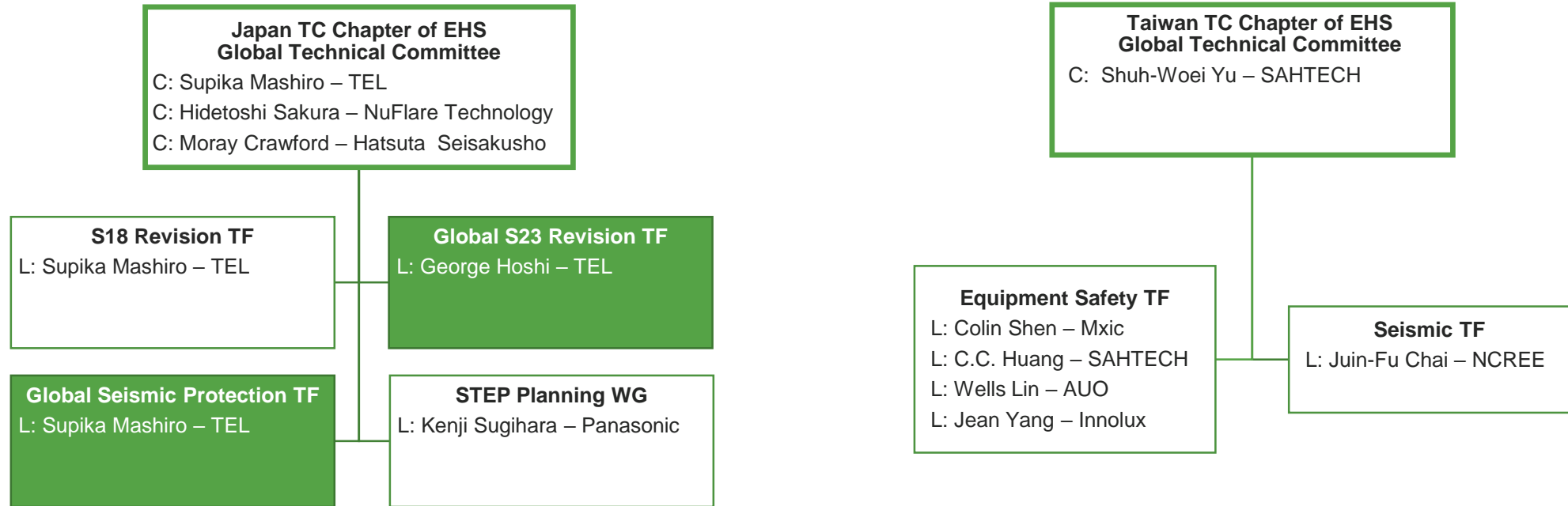


# Compound Semiconductor Materials (CSM) Global Technical Committee



# Environmental, Health & Safety (EH&S)

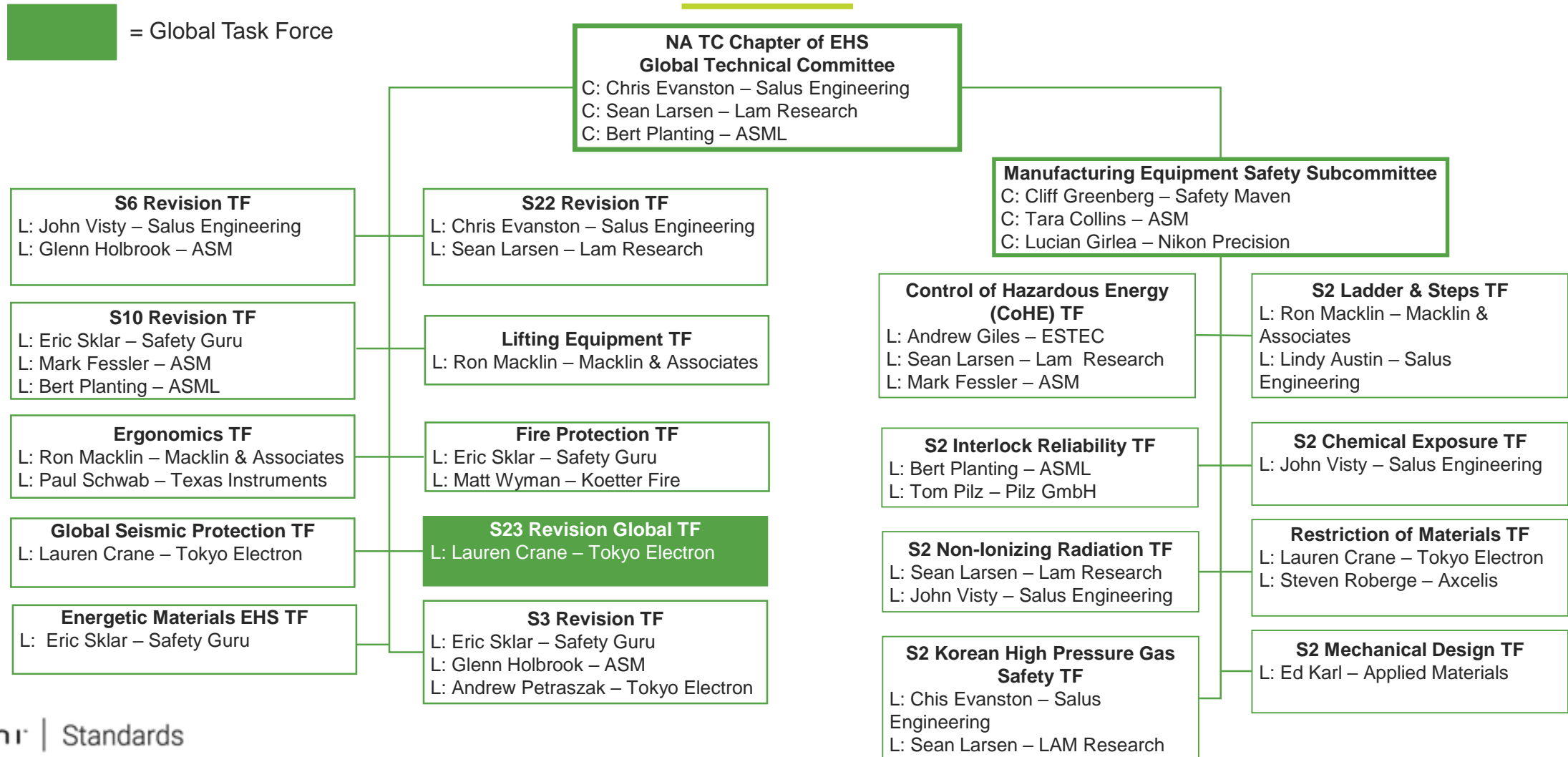
## Global Technical Committee



 = Global Task Force

# Environmental, Health & Safety (EH&S)

## Global Technical Committee



# Facilities

## Global Technical Committee

---

**Japan TC Chapter of Facilities  
Global Technical Committee**  
C: Hiromichi Enami – Consultant  
C: Isao Suzuki – Consultant  
C: Masafumi Kitano – Fujikin

**F1 Revision TF**  
L: Masafumi Kitano – Fujikin  
L: Kazuhiko Takamisawa –  
NISSAN TANAKA

**5-Year Review TF**  
L: Masafumi Kitano – Fujikin

**NA TC Chapter of Facilities  
Global Technical Committee**  
C: Steve Lewis – BW Design Group

**F51 Revision TF**  
L: Dalia Vernikovsky – Applied  
Seals North America

**Building Information Modeling  
(BIM) for Semiconductor Capital  
Equipment TF**  
L: Ben Bruce – Applied Materials

**Power Grid Harmonics TF**  
L: Alex McEachern – Power  
Standards Lab

**Voltage Sag Immunity TF**  
L: Mark Stephens – EPRI

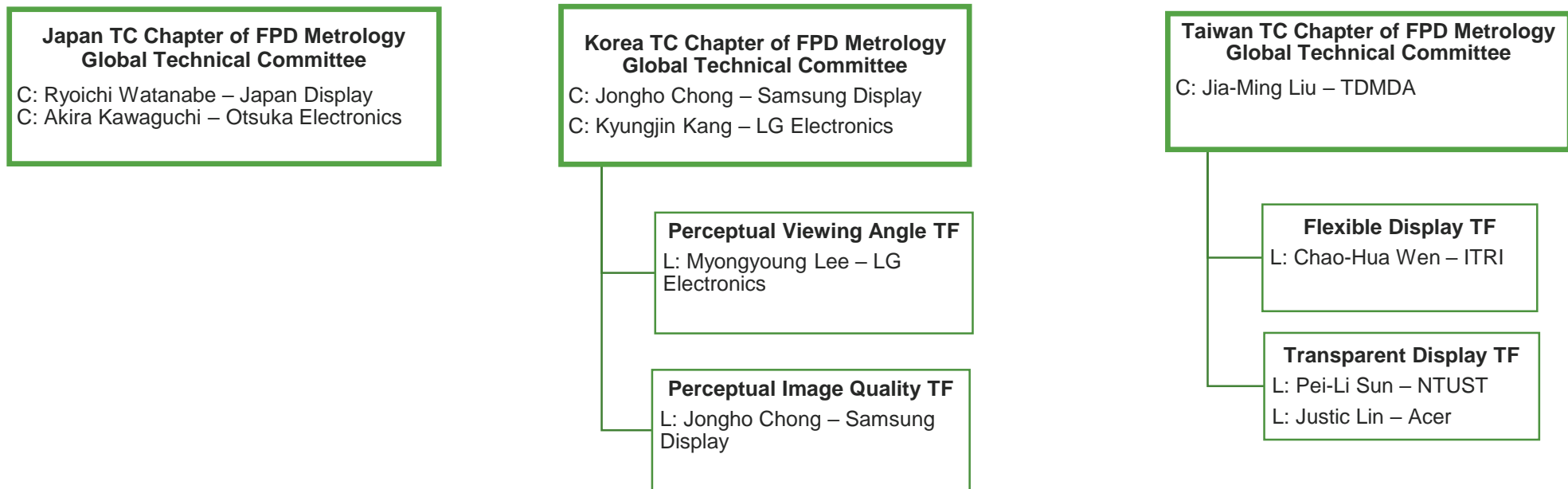
**Korea TC Chapter of Facilities  
Global Technical Committee**  
C: Kwang Sun Kim – KUT

**Equipment Cleanness TF**  
L: TBD

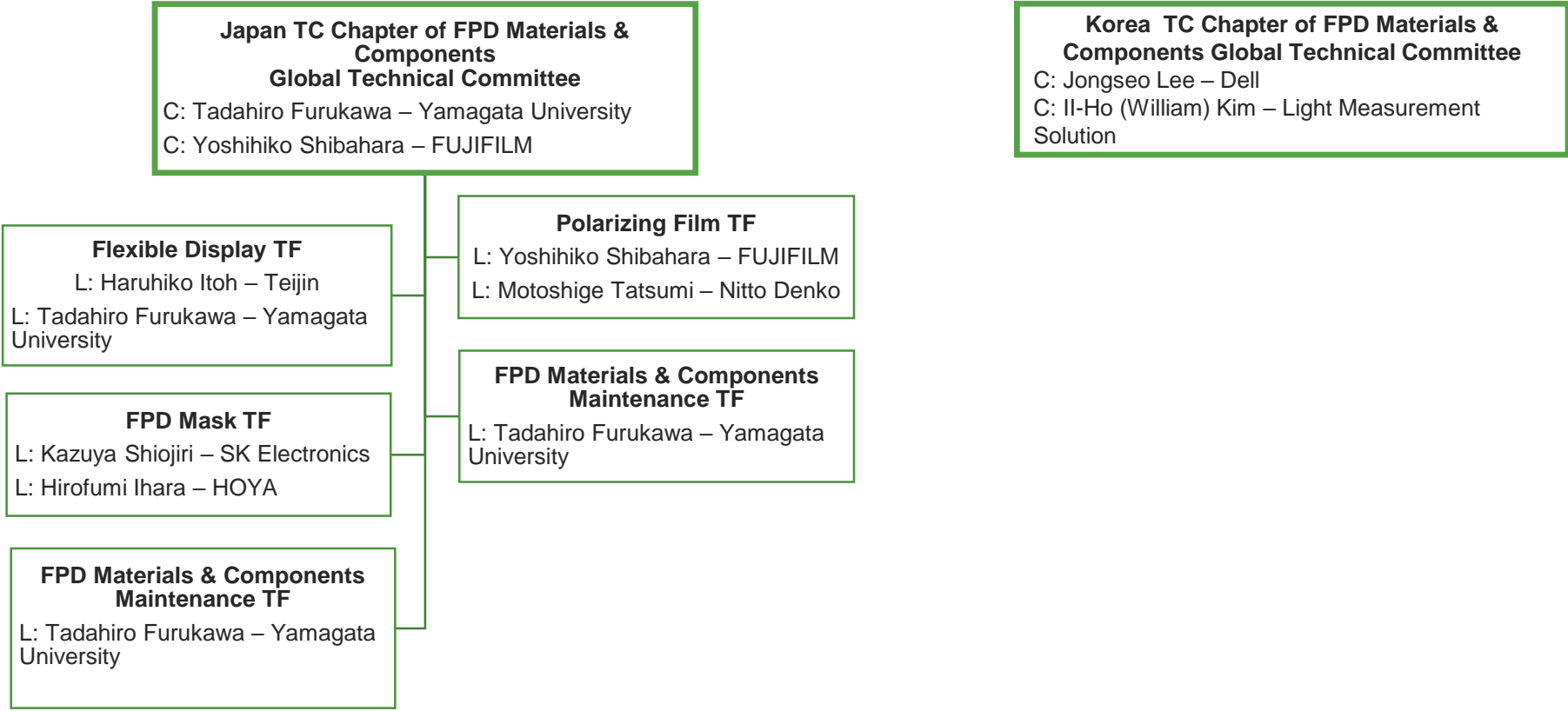
# FPD Metrology

## Global Technical Committee

---



# FPD Materials & Components Global Technical Committee



# Gases

## Global Technical Committee



**Europe TC Chapter of Gases  
Global Technical Committee**  
C: Jochen Ruth – Pall Corporation

**Permeation Tubes for Trace  
Moisture Calibration TF**  
L: Jean-Marie Collard – Solvay Chemicals  
L: Jim McKinley – KIN-TEK

**Cleaning Gases TF**  
L: Jean-Marie Collard – Solvay Chemicals

**Japan TC Chapter of Gases  
Global Technical Committee**  
C: Hiromichi Enami – Consultant  
C: Isao Suzuki – Consultant  
C: Masafumi Kitano – Fujikin

**NA TC Chapter of Gases  
Global Technical Committee**  
C: Mohamed Saleem – Brooks Instrument

**Filters & Purifiers TF**  
L: Mohamed Saleem – Brooks Instrument  
L: Yanli Chen – AMAT

**Heater Jacket TF**  
L: David Colquhoun – BriskHeat

**Mass Flow Controller TF**  
L: Mohamed Saleem – Brooks Instrument

**Gases Specification TF**  
L: Mohamed Saleem – Brooks Instrument  
L: Thomas Fritz – WIKA

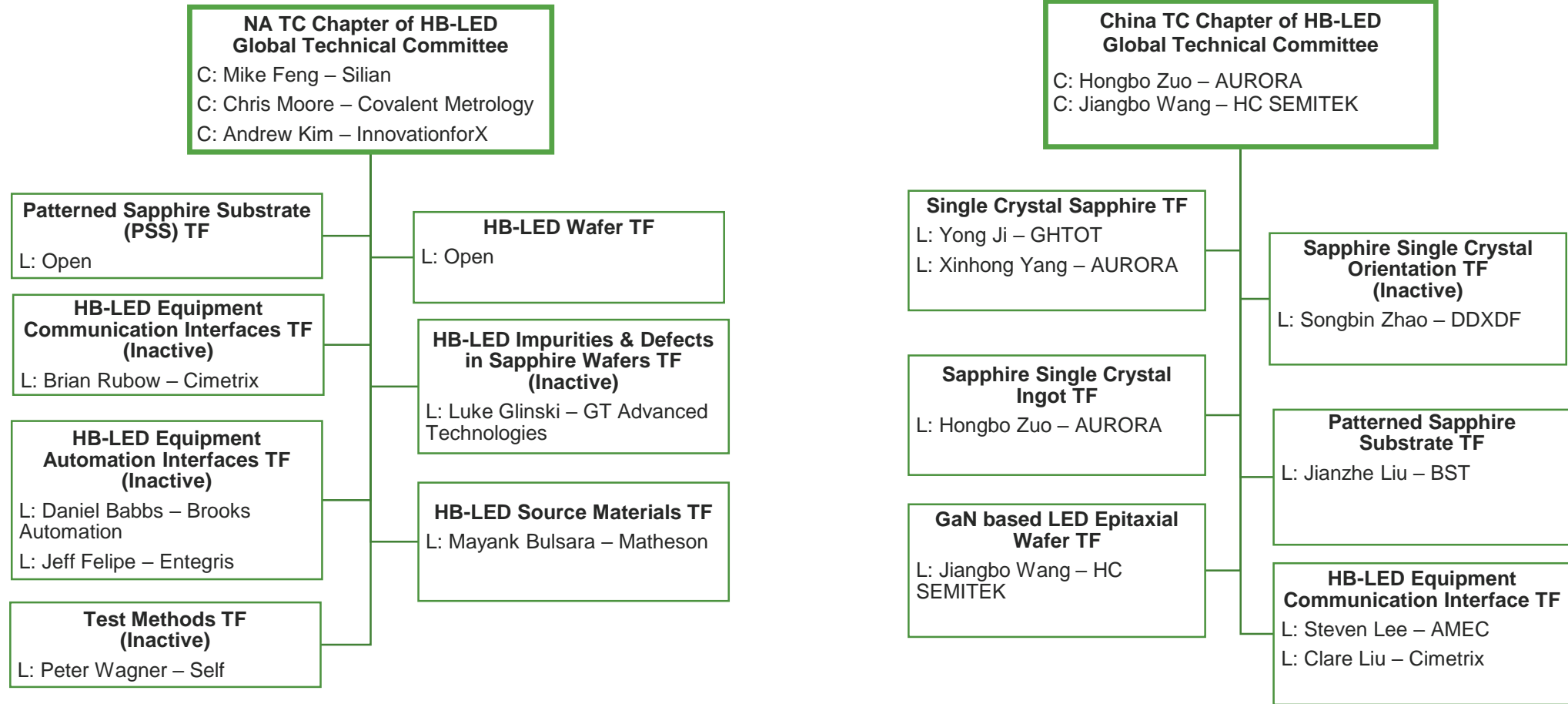
**Materials of Construction  
Gas Delivery Systems TF**  
L: Bill Kiikvee – AP Tech

**Pressure Measurement TF  
(Inactive)**  
L: Yanli Chen – AMAT  
L: Jeff Christian – WIKA

**Surface Mount Sandwich  
Component Dimensions TF  
(Inactive)**  
L: Matt Milburn – UCT

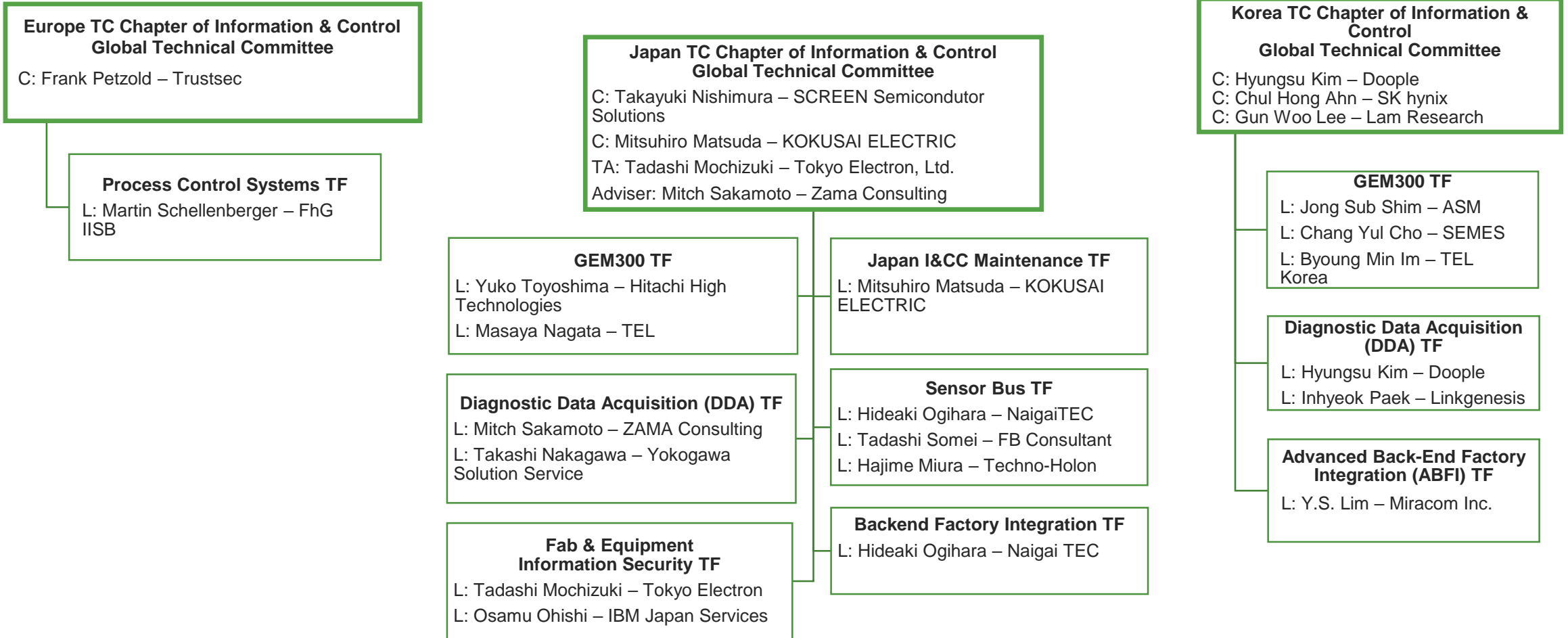
# HB-LED

## Global Technical Committee



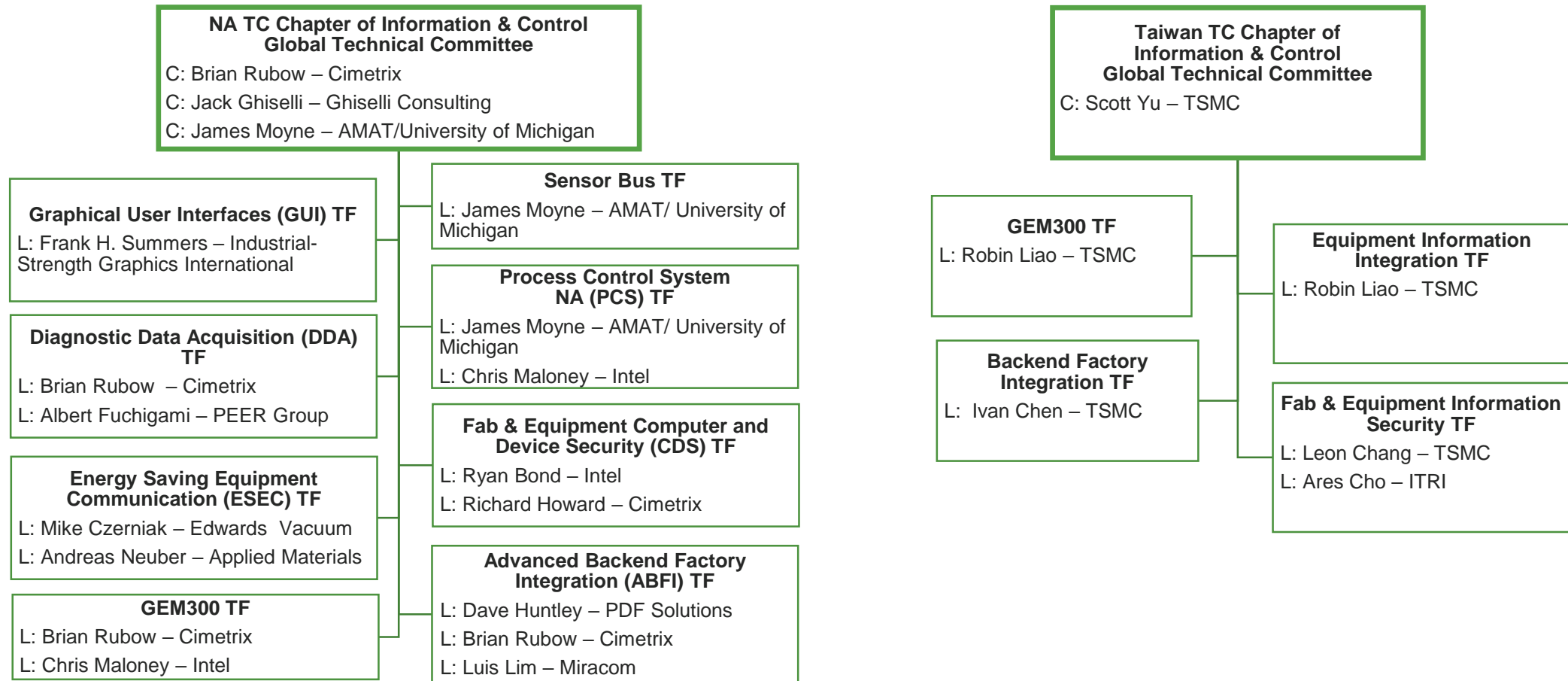


# Information & Control (I&C) Global Technical Committee



# Information & Control (I&C)

## Global Technical Communities



# Liquid Chemicals

## Global Technical Committee



**Europe TC Chapter of Liquid Chemicals Global Technical Committee**  
 C: Jochen Ruth – Pall Corporation

**Precursor Specifications TF**  
 L: Paul Williams – SAFC Hitech

**Solvents in Advanced Processes TF**  
 L: TBD

**Japan TC Chapter of Liquid Chemicals Global Technical Committee**  
 C: Hiroshi Tomita – KIOXIA  
 C: Hiroyuki Araki – SCREEN Semiconductor Solutions

**Liquid Filter TF**  
 L: Takuya Nagafuchi – Nihon Entegris  
 L: Tomoyuki Takakura – Pall

**Diaphragm Valve TF**  
 L: Shigeru Ohsugi – CKD  
 L: Kimihito Sasao – Advance Electric

**Trace Metal Analysis for High Pure IPA TF**  
 L: Takuya Nagafuchi – Nihon Entegris  
 L: Hiroshi Sugawara – Organo

**Liquid-Borne Particle Counter TF**  
 L: Kaoru Kondo – RION  
 L: Kazutoshi Kato – PMS Division/Spectris Co., Ltd.

**Welding Fitting TF**  
 L: Kimihito Sasao – Advance Electric  
 L: Takashi Hasegawa – KITZ SCT

**Ultrapure Liquid Evaluation Study Group**  
 L: Kaoru Kondo – RION  
 L: Hiroshi Sugawara – ORGANO

**NA TC Chapter of Liquid Chemicals Global Technical Committee**  
 C: Don Hadder – Intel  
 C: Steve Rogers – KMG Chemicals  
 C: Laura Ledenbach – PeroxyChem  
 C: Koh Murai – Mega Fluid Systems

**Chemical Analytical Methods (CAM) TF**  
 L: Don Hadder – Intel  
 L: David Kandiyeli – Mega Fluid Systems

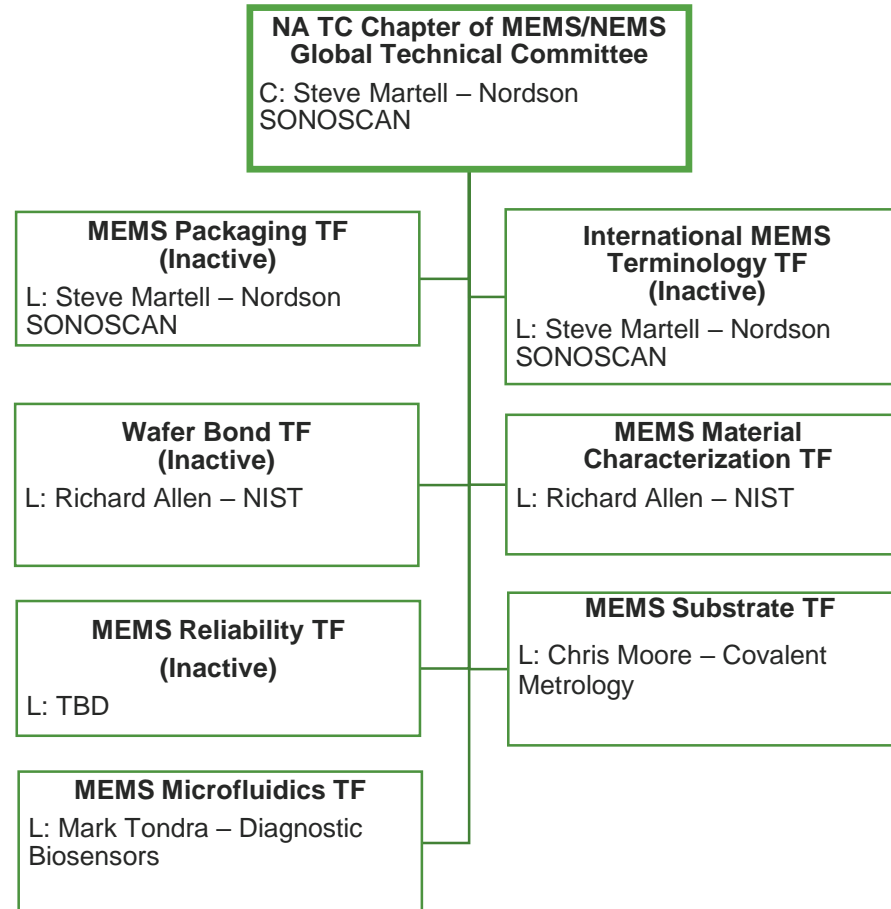
**High Purity Liquid Assemblies & Systems TF (Inactive)**  
 L: Koh Murai – Mega Fluid Systems  
 L: David Kandiyeli – Mega Fluid Systems

**High Purity Polymer Materials & Components TF**  
 L: Bob McIntosh – GF Piping

**Ultra Pure Water (UPW) TF**  
 L: Slava Libman – FTD Solutions  
 L: Bob McIntosh – GF Piping

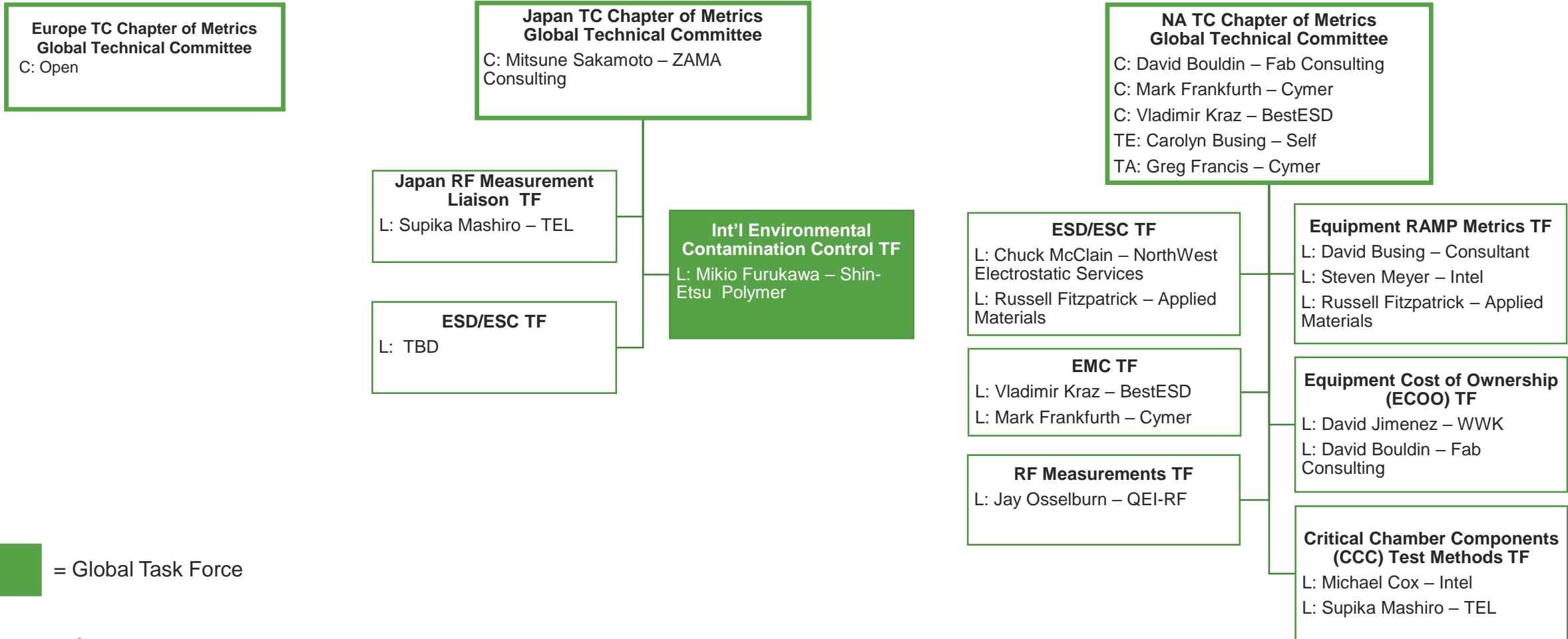
# MEMS/NEMS


## Global Technical Committee



# Metrics

## Global Technical Committee

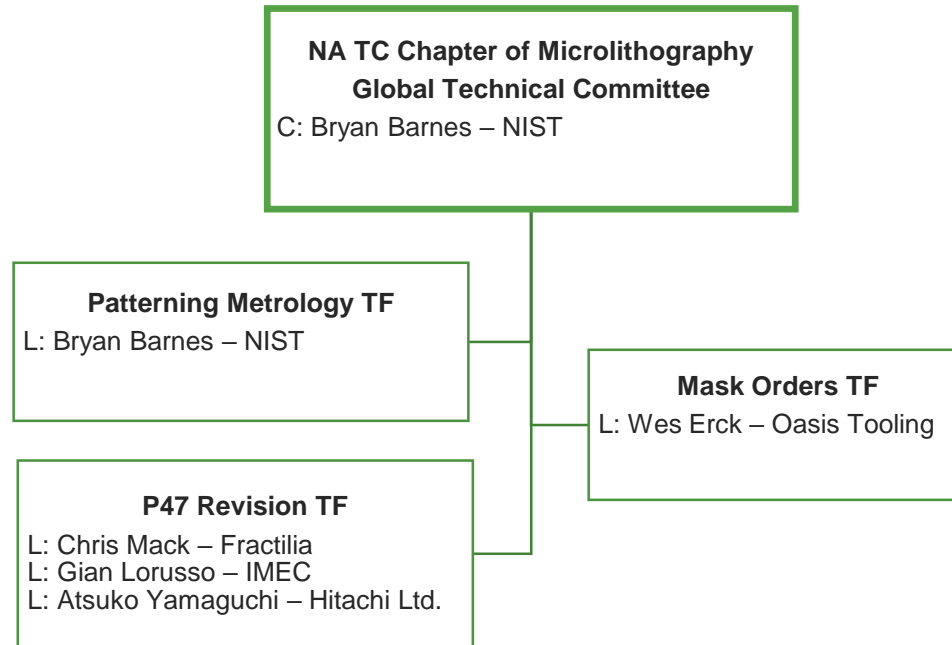


 = Global Task Force

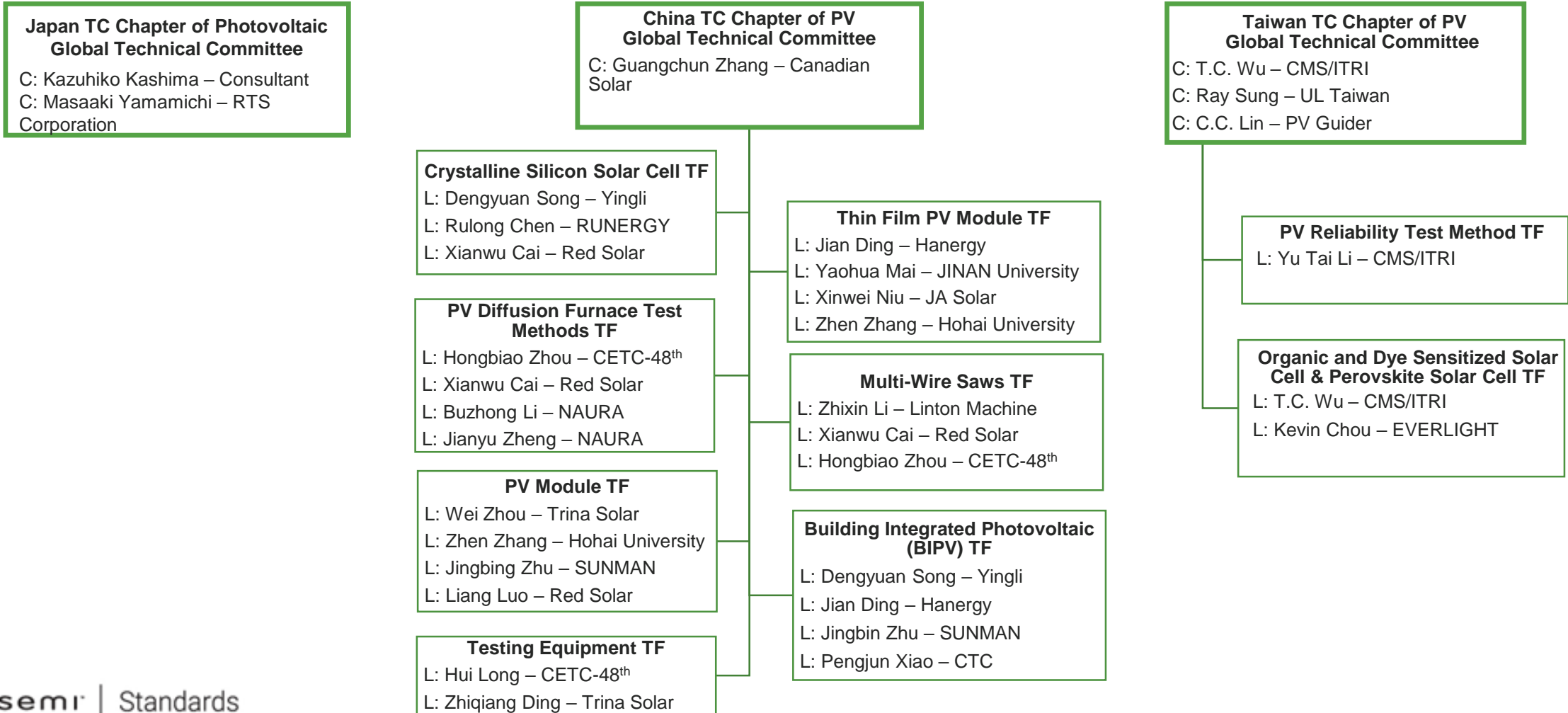
# Micropatterning

## Global Technical Committee

---

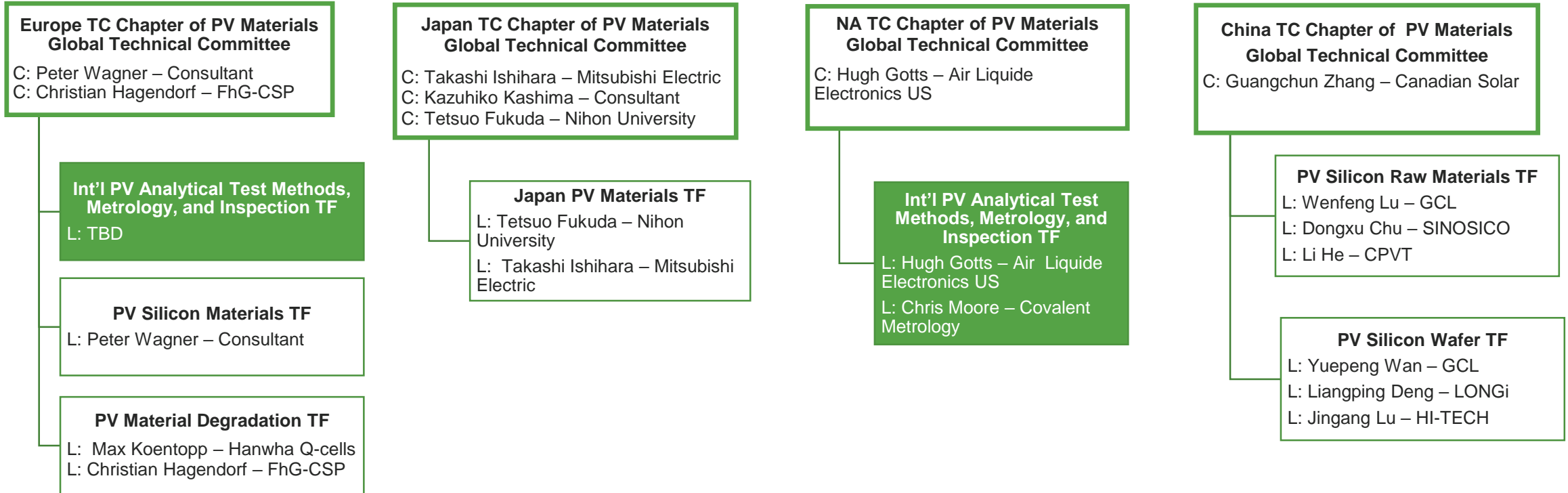



# Photovoltaic (PV) Global Technical Committee



# PV Materials

## Global Technical Committee

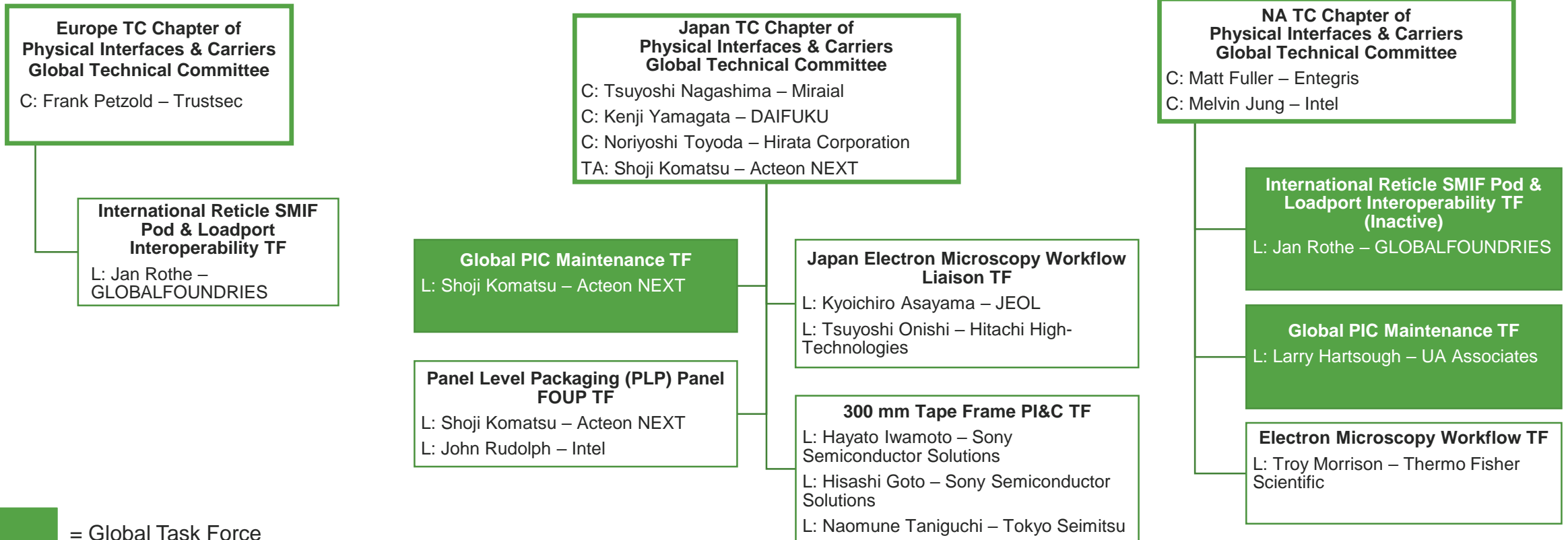


 = Global Task Force

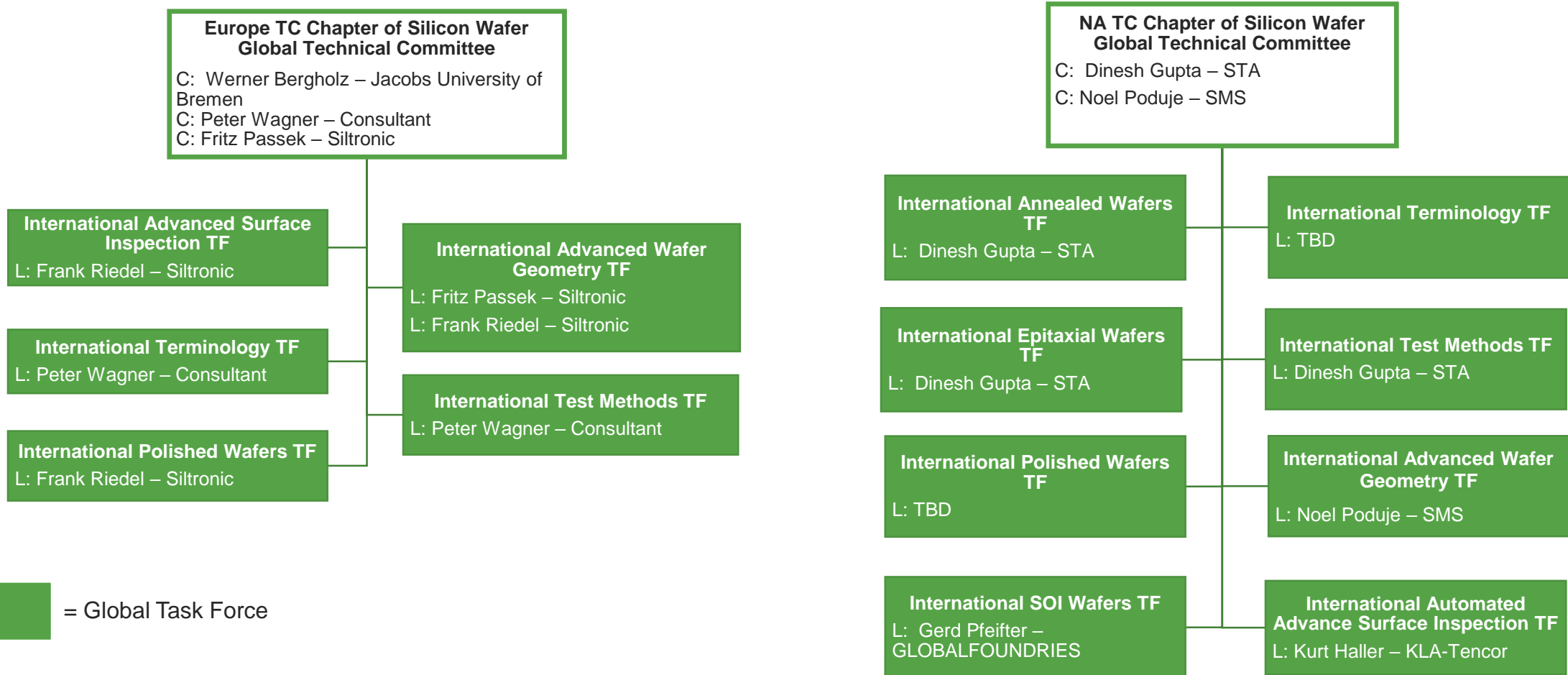


# Physical Interfaces & Carriers (PI&C)

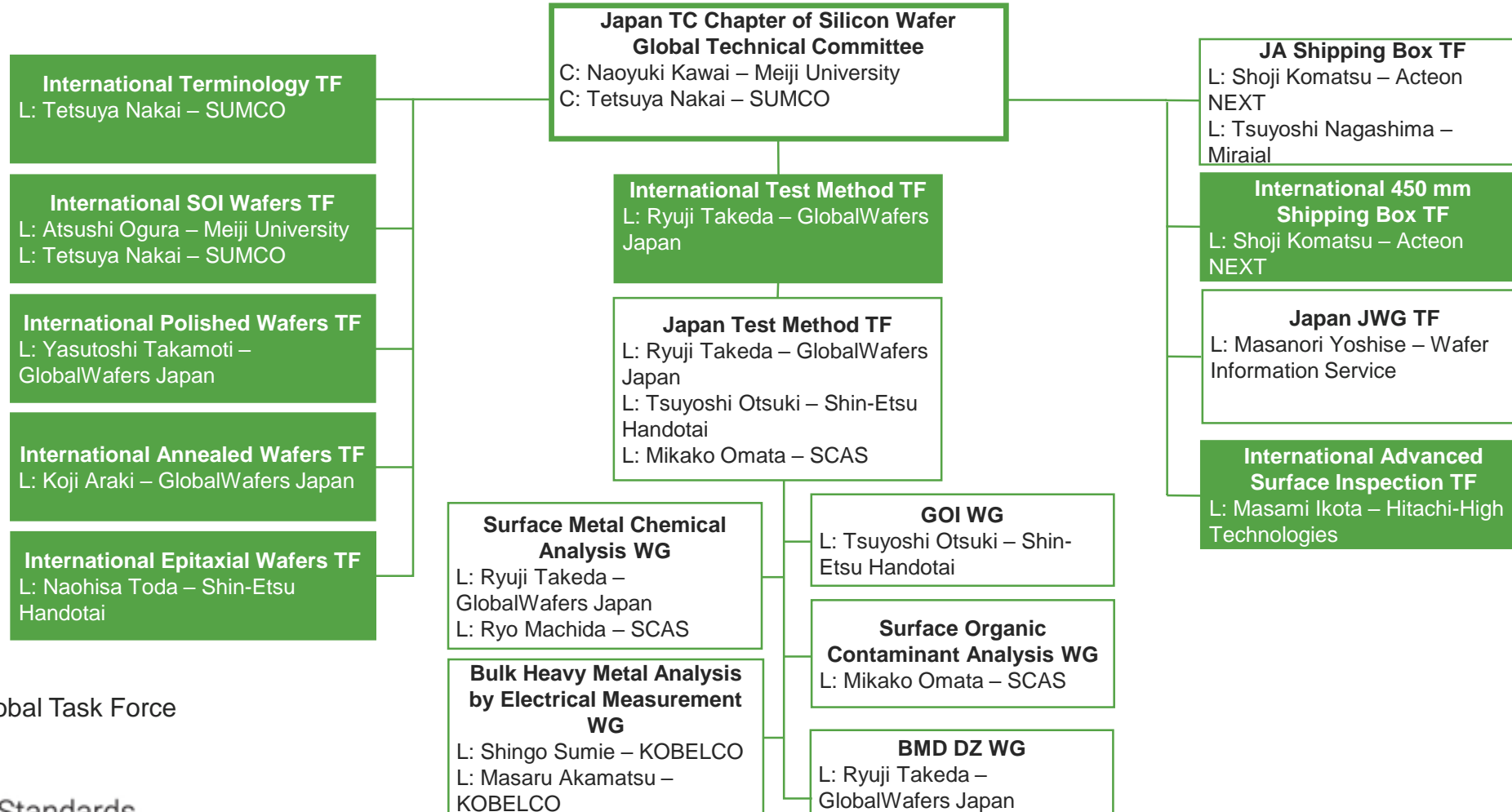
## Global Technical Committee



# Silicon Wafer Global Technical Committee



# Silicon Wafer Global Technical Committee



 = Global Task Force

# Traceability

## Global Technical Committee

---

